

Features

- Very High Speed Operation 3.3GHz
- Silicon Technology for low Phase Noise (Typically better than -140dBc/Hz at 10kHz)
- Specified Over the Full Military Temperature Range
- Low Power Dissipation 345mW (typ)
- 5V Single Supply Operation
- High Input Sensitivity
- Very Wide Operating Frequency Range
- Available as DESC SMD 5962-9157001MPA

Description

The SP8808 is one of a range of very high speed low power prescalers for professional and military applications. The device features a complementary output stage with on chip current source for the emitter follower outputs.

DS2113

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Ordering Information

SP8808/A/DG Military temperature range
DES9157001/AC/DGAZ (SMD)

Thermal Characteristics

$\theta_{ja} = 150^{\circ}\text{C/W}$

$\theta_{jc} = 50^{\circ}\text{C/W}$

Absolute Maximum Ratings

Supply voltage V_{CC}	6.5V
Clock Input voltage	2.5V p-p
Storage temperature range	-65°C to +150°C
Junction temperature	+175°C

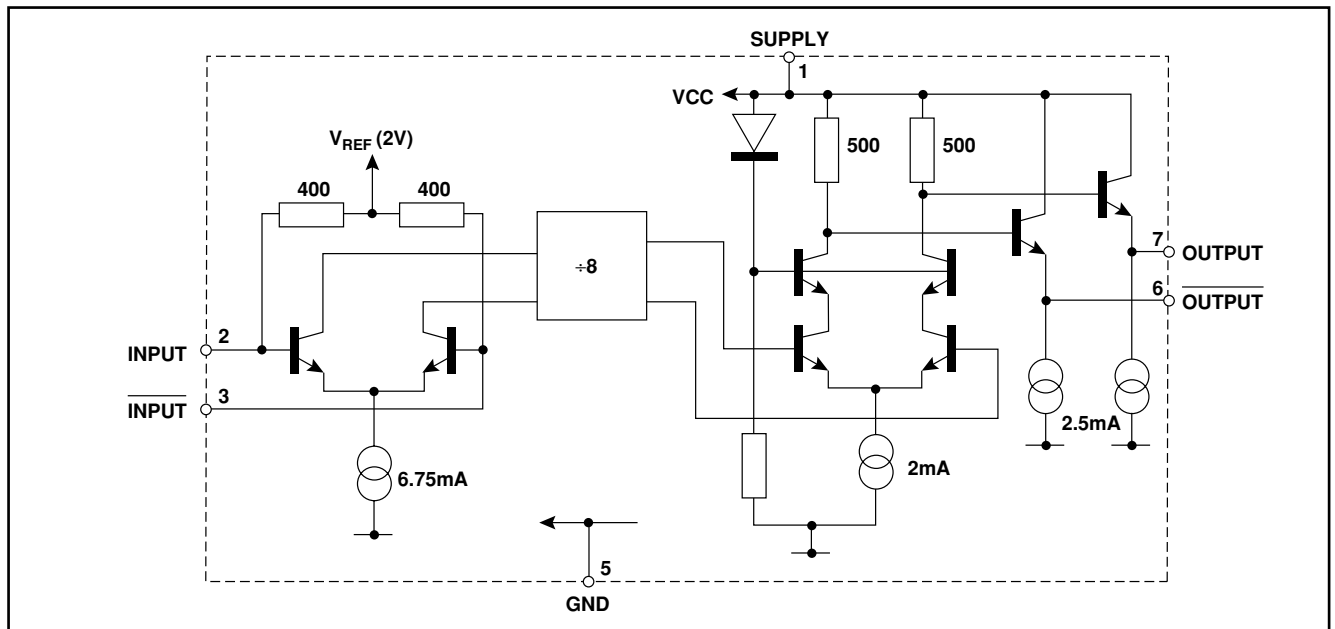


Figure 1 - SP8808 Block diagram

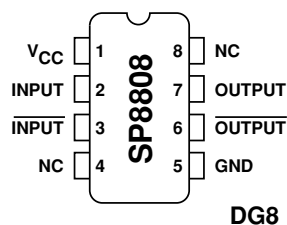


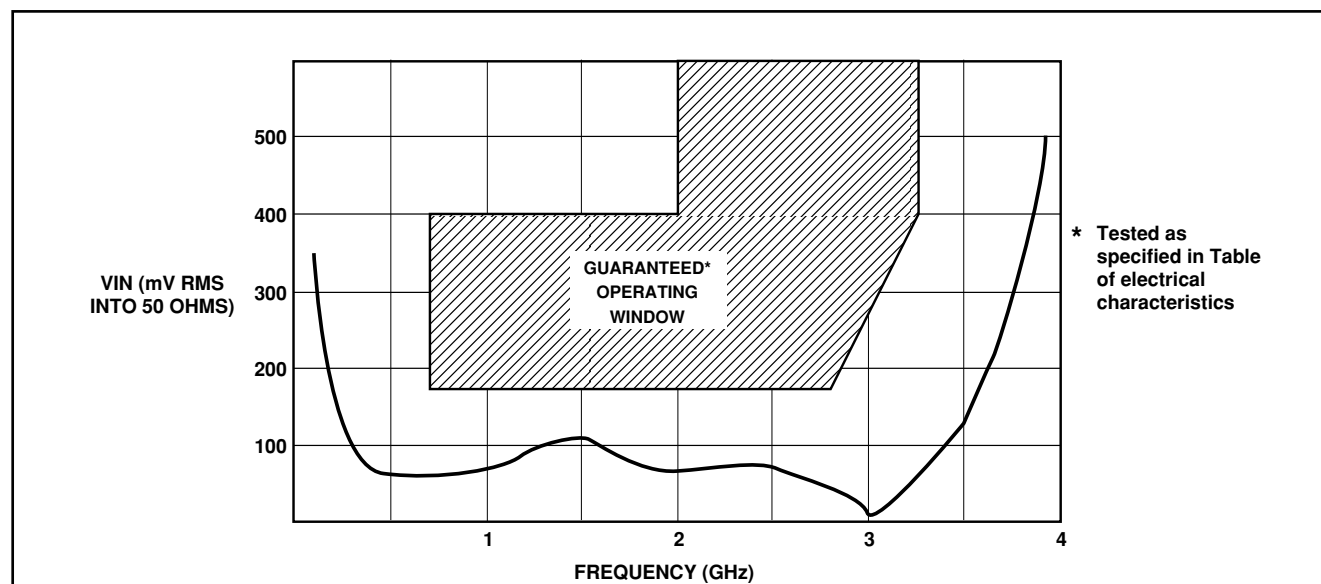
Figure 2 - Pin connections

Electrical Characteristics

Guaranteed over the temperature range T_{amb} -55°C to +125°C (see note) and supply voltage range 4.75V to 5.25V. Tested at T_{amb} = -55°C and +110°C, V_{CC} = 4.75V and 5.25V.

Characteristic	Pin	Value			Units	Conditions
		Min	Typ	Max		
Supply current	1		69	85	mA	$V_{CC} = 5V$
Input sensitivity	2, 3			175	mV	RMS sinewave
0.65GHz to 2.8GHz				400	mV	measured in 50 ohm system.
3.3GHz					Ω	See Figs. 3 & 4
Input impedance (series equivalent)	2, 3		50		pF	
			2			
Output Voltage with $f_{in} = 1000MHz$	6, 7	0.8	1		Vp-p	$V_{CC} = 5V$
Output Voltage with $f_{in} = 3GHz$	6, 7		0.4		Vp-p	$V_{CC} = 5V$ load as Fig. 4

NOTE: Devices must be used with a suitable heatsink to maintain chip temperature below 175°C when operating at $T_{amb} > 110^\circ C$.



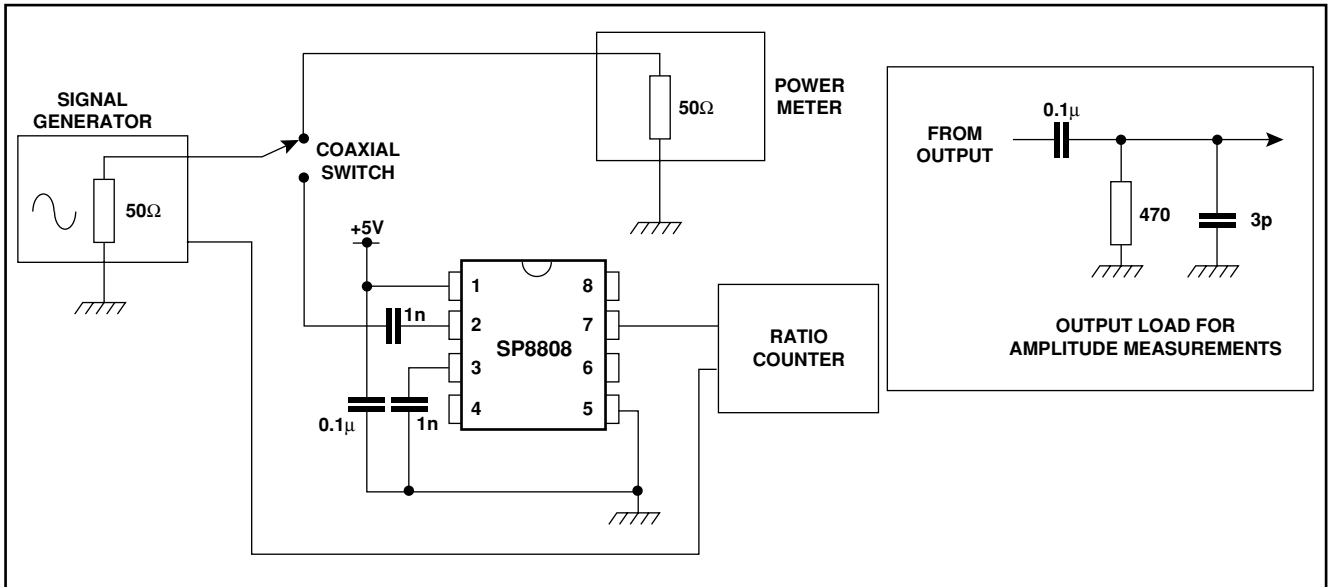


Figure 4 - Test circuit

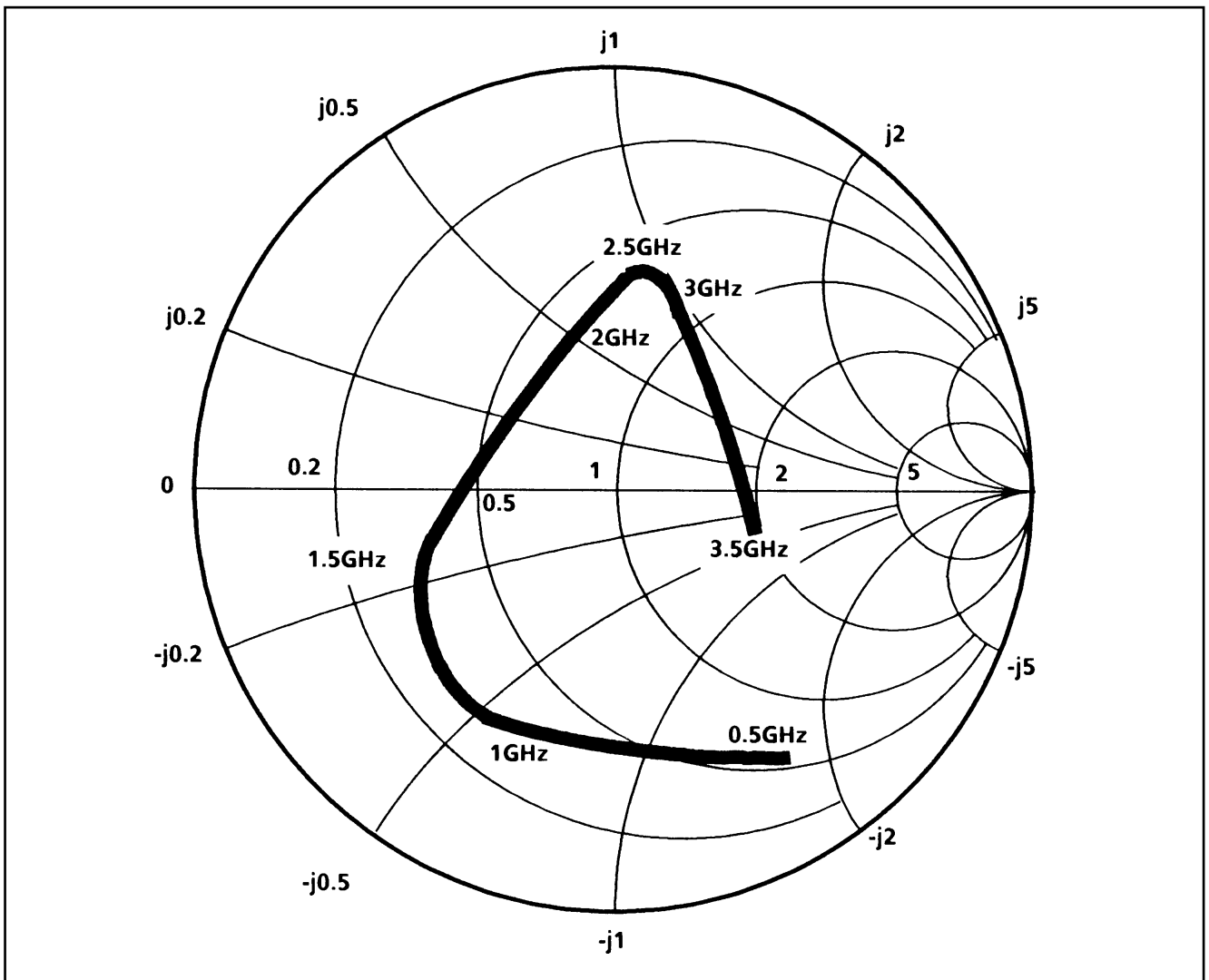
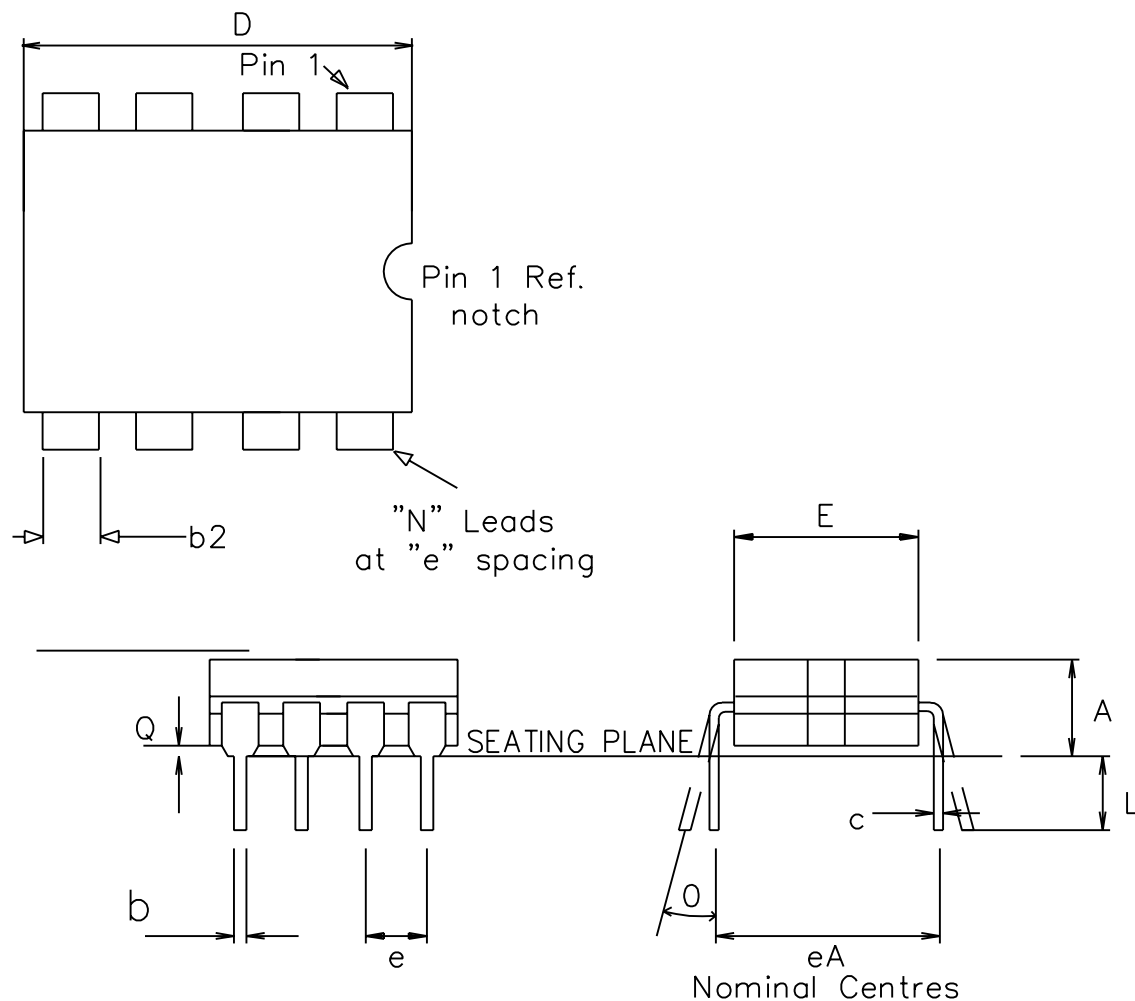



Figure 5 - Typical input impedance



Symbol	Altern. Dimensions in millimetres			Control Dimensions in inches		
	MIN	Nominal	MAX	MIN	Nominal	MAX
L	3.18		4.06	0.125		0.160
A			5.08			0.200
Q	0.51			0.020		
E	5.59		7.87	0.220		0.310
eA		7.62			0.300	
c	0.20		0.36	0.008		0.014
D			10.29			0.405
e	2.54 BSC.			0.100 BSC.		
b2	1.14		1.65	0.045		0.065
b	0.36		0.58	0.014		0.023
0			15			15
Pin features						
N	8					
ND	4					
NE	0					
NOTE	RECTANGULAR					

This drawing supersedes 418/ED/39501/001 (Swindon)

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